Revision: 31-Jan-2020

1 For technical questions, contact: sferthinfilm@vishay.com

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Note

⁽¹⁾ With special assembly care

CLIMATIC SPECIFICATIONS				
Operating temperature range	-55 °C; +155 °C			

MECHANICAL SPECIFICATIONS					
Substrate Alumina					
Technology NiCr + Ta ₂ O ₅					
Coating	pating Silicone				
Terminations	Solderable B type: SnPb over nickel barrier N type: SnAg over nickel barrier G type: Gold over nickel barrier				

Note

Refer to Application Note "Guidelines for Vishay Sfernice Resistive and Inductive Components" (document number: 52029) for recommended reflow profile. Profile #3 applies

•	Material	categ	porization:	tor	defini	tions	(
	please s	ee <u>ww</u>	w.vishay.o	com/o	doc?99	<u>9912</u>	
Ν	ote						
*	This dat	asheet	provides	inforr	mation	about	
	RoHS-co	mpliant	and / or pa	irts tha	at are n	on Rol	15
	example,	parts w	ith lead (Pb)) termi	nations	are no	tl
		·	C	1 - 1 - 1			

 NiCr + Ta₂O₅ resistive layer
 Pre-soldered or gold terminations
 No inductance for high frequency applications

			-	•		
•	Alumina	substrates	for	high	power	handling
	capabilit	У				

- Resistance range: 0.1 Ω to 9.99 Ω
- TCR down to 50 ppm/°C

FEATURES

- Power rating: up to 2 W at +70 °C
- Withstand AEC-Q200 humidity test
- dafiniti ootoovizatio s. fa of compliance

parts that are S-compliant. For RoHS-compliant. Please see the information / tables in this datasheet for details

TOLERANCE AND TCR VS. OHMIC VALUE

BEST

TCR

(ppm/°C)

300

200

100

50

300

200

100

100

50

TIGHTEST

TOLERANCE

(%)

1

1

1

1

5

5

5

3

3

OHMIC VALUE

RANGE in Ω

0R1 < 0R25

0R25 < 0R5

0R5 < 2R5

2R5 < 9R99

0R1 < 0R25

0R25 < 0R5

0R < 1R

1R < 2R5

2R5 to 9R99

STANDAR	STANDARD ELECTRICAL SPECIFICATIONS							
MODEL	SIZE	$\begin{array}{c} \textbf{RESISTANCE RANGE}\\ \Omega \end{array}$	RATED POWER P _{70 °C} W	LIMITING ELEMENT VOLTAGE V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C		
L0603	0603	0.1 to 9.99	0.125	50	1, 2, 3, 5, 10	50, 100, 200, 300		
L0805	0805	0.1 to 9.99	0.2	50	1, 2, 3, 5, 10	50, 100, 200, 300		
L1206	1206	0.1 to 9.99	0.33	50	1, 2, 3, 5, 10	50, 100, 200, 300		
L1505	1505	0.1 to 9.99	0.5	50	1, 2, 3, 5, 10	50, 100, 200, 300		
L2010	2010	0.1 to 9.99	1.0	50	1, 2, 3, 5, 10	50, 100, 200, 300		
L2512	2512	0.1 to 9.99	2.0 (1)	50	1, 2, 3, 5, 10	50, 100, 200, 300		

SMD Wraparound Ultra Low Value Thin Film Resistors

www.vishay.com

ADDITIONAL RESOURCES



With extremely low resistance and high power capabilities, these ultra low value resistors are available with solderable or weldable terminations.

Vishay Sfernice

TERMINATIONS

N or B

N or B

N or B

N or B

G

G

G

G

G



HALOGEN FREE GREEN

(5-2008)



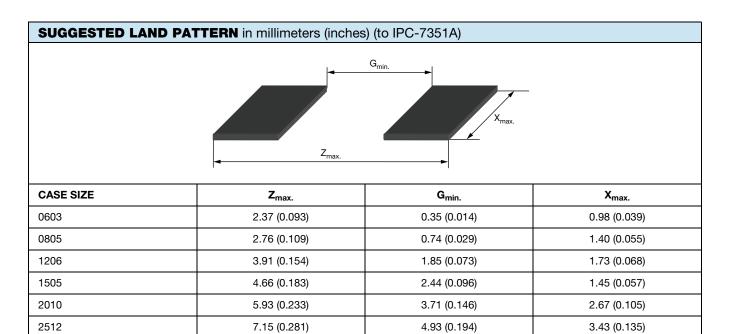
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DIMENSIONS in millimeters (inches)



	A	В	С	D/E			
CASE SIZE	± 0.152 (± 0.006)	± 0.127 (± 0.005)	± 0.127 (+ 0.005)	± 0.127 (± 0.005)			
0603	1.52 (0.060)	0.85 (0.033)		0.00 (0.015)			
0805	1.91 (0.075)	1.27 (0.050)		0.38 (0.015)			
1206	3.06 (0.120)	1.60 (0.063)	0.5 (0.000)	0.40 (0.016)			
1505	3.81 (0.150)	1.32 (0.052)	- 0.5 (0.020)				
2010	5.08 (0.200)	2.54 (0.100)		0.48 (0.019)			
2512	6.30 (0.248)	3.30 (0.129)					



Option: Enlarged Terminations: 0063

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heat sinks (see application note: "Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film)": www.vishay.com/doc?53048).

For enlarged terminations: Please consult Vishay Sfernice.

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60 70 80

Can be filled up to maximum quantity indicated in the table

here above, taking into account the minimum order quantity.

When quantity ordered exceeds maximum quantity of a

single waffle pack, the waffle packs are stacked up on the

To get "not stacked up" waffle pack in case of ordered

quantity > maximum number of pieces per package:

Please consult Vishay Sfernice for specific ordering

top of each other and closed by one single cover.

100

120

Ambient Temperature in °C

140 155

POWER DERATING CURVE

Rated Power (%) 0 00 00

60

40

20

0

Waffle Pack

code.

0

PACKAGING RULES

20

40

3

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PACKAGING

Several types of packaging are proposed: waffle-pack and tape and reel

		NUMBER PER P	OF PIECI ACKAGE	ES	TAPE	
SIZE	MOQ	WAFFLE PACK	TAPE A	ND REEL	WIDTH	
		2" × 2"	MIN.	MAX.		
0603		100		5000	8 mm	
0805		100		4000		
1206	100	140	100			
1505	100	60	100			
2010		00		2000		
2512		50		2000		

Tape and Reel

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided.

When several reels are needed for ordered quantity within MOQ and maximum reel capacity: Please consult Vishay Sfernice for specific ordering code.

PERFORMANCE					
		VALUES AND DRIFT			
TESTS	CONDITIONS	MIL-R-55342 REQUIREMENTS	TYPICAL PERFORMANCES		
Thermal shock	MIL-R-55342 C MIL-STD-702, method 107	± 0.25 %	± 0.02 %		
Short time overload	MIL-R-55342 C PARA 3.10.4.7.5	± 0.10 %	± 0.01 %		
Low temperature operation	emperature operation MIL-R-55342 C ± 0.25 % ± 0.01 9		± 0.01 %		
Resistance to solder heat	MIL-R-55342 C PARA 3.12, 4.7.7, 4.7.1.2	± 0.25 %	± 0.04 %		
Moisture resistance	MIL-R-55342 C PARA 3.13 and 4.7.8 MIL-STD-202, method 106	± 0.40 %	± 0.01 %		
Moisture resistance	AEC-Q200 85 °C / 85 % RH / 0.1 Pn 1000 h	-	Max. < 0.5 % + 0.05 Ω		
High temperature	MIL-R-55342 C PARA 3.11 and 4.7.6	± 0.20 %	± 0.075 %		
Load life	MIL-R-55342 C 2000 h Pn at 70 °C MIL-STD-202, method 108	± 0.50 % ± 0.15 %			

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SHAY

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GLOBAL P	GLOBAL PART NUMBER INFORMATION						
L 0 8 0 5 K 1 R 0 0 F B T 0 0 9 9							
GLOBAL MODEL	SIZE	TCR	VALUE	TOLERANCE	TERMINATION	(1) PACKAG	ING OPTION
	0603 0805 1206 1505 2010 2512	$H = \pm 50 \text{ ppm}$ $K = \pm 100 \text{ ppm}$ $L = \pm 200 \text{ ppm}$ $M = \pm 300 \text{ ppm}$	R designated decimal point For values under 1R Rxxx	J = ± 5 % K = ± 10 %	B: SnPb over nickel barrier N: SnAg over nickel barrier G: gold over nickel barrier	information Codification Packagi table	n see blank if on of no ng option
Historical Pai	rt Number Exa	mple: L 0805 K 1	R00 1 % B T R009	9			
L	0805	к	1R00	1 %	В	т	R0099
MODEL	SIZE	TCR	VALUE	TOLERANCE	TERMINATION	PACKAGING	OPTION

Note

⁽¹⁾ B: lead bearing version N and G: lead (Pb)-free / RoHS version

CODIFICATION OF PACKAGING						
CODE 18	PACKAGING					
WAFFLE PACK						
W	100 min., 1 mult.					
WA	100 min., 100 mult. (available only in size 1206)					
PLASTIC TAPE (Standard for all s	sizes)					
Т	100 min., 1 mult.					
ТА	100 min., 100 mult.					
ТВ	250 min., 250 mult.					
TC	500 min., 500 mult.					
TD	1000 min., 1000 mult.					
TE	2500 min., 2500 mult.					
TF	Full tape (quantity depending on size of chips)					
PAPER TAPE (Available for 0603,	0805, and 1206. Please consult Vishay Sfernice for other sizes)					
PT	100 min., 1 mult.					
PA	100 min., 100 mult.					
PB	250 min., 250 mult.					
PC	500 min., 500 mult.					
PD	1000 min., 1000 mult.					
PE	2500 min., 2500 mult.					
PF	Full tape (quantity depending on size of chips)					

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